

ABSTRACT OF THE DISCLOSURE

An integrated circuit package including an optical sensor array is provided with a transparent window comprising a thermoset plastic, such as an epoxy transfer clear molding compound, that is resistant to the elevated temperatures found in semiconductor processing and is configured as a lens, to improve the image quality of the image incident on the sensor. As an example, a field flattener lens is incorporated into the window to form an integral element that also acts as an hermetic seal. Thus, the field flattener is made integral with the sensor. The thermoset lens provides two functions: (1) it improves the image quality; and (2) it protects the sensor from damage and contamination. This protection is normally provided by a glass window on the sensor, but is no longer necessary by virtue of the present invention.